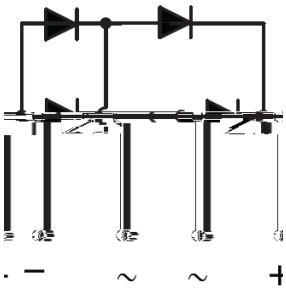
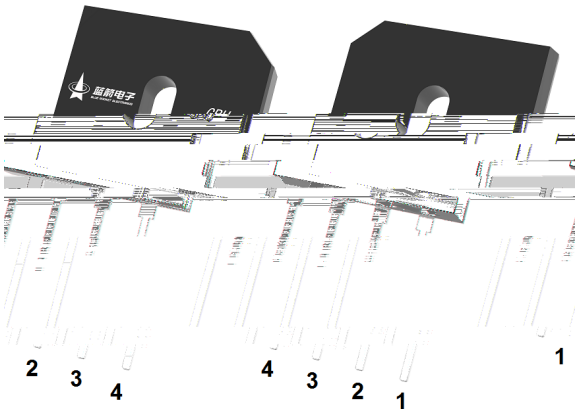
8.0A 50~1000V GBU
8 0 : 0 1000

9 0

9 0





1 2 3

1

		800	801	802	80	806	808	810
		0	100	200	00	600	800	1000
		3	70	1 0	280	20	60	700
		0	100	200	00	600	800	1000
=100 ( )	( )	8 0						
( )		17						

(<8 3) 2 127 2

/ Electrical Characteristic Curve

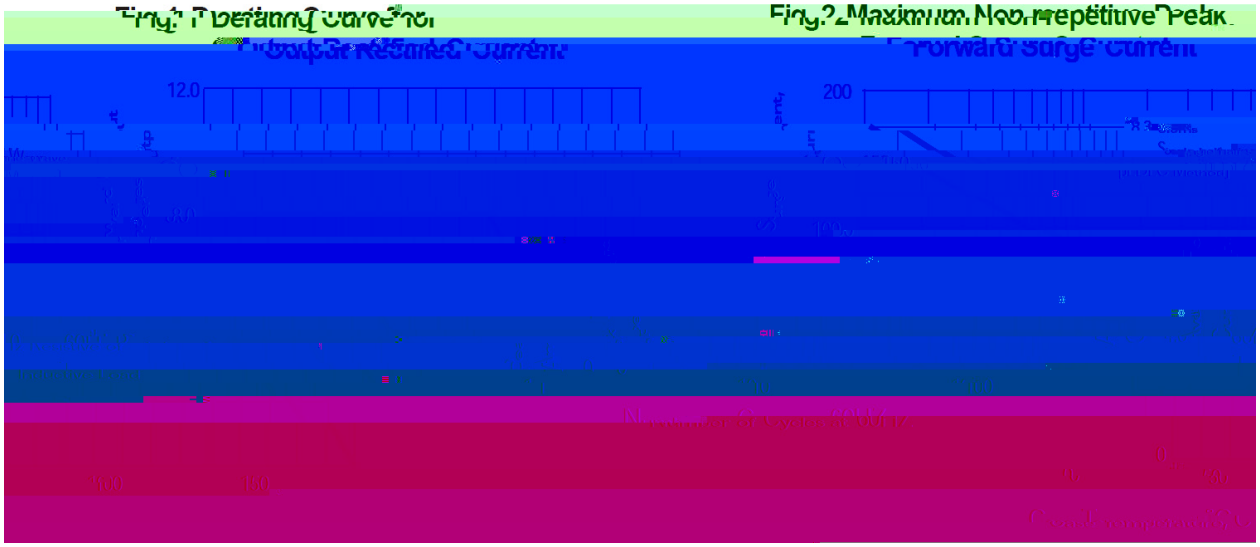


Fig. 3 Typical Instantaneous Forward Characteristics

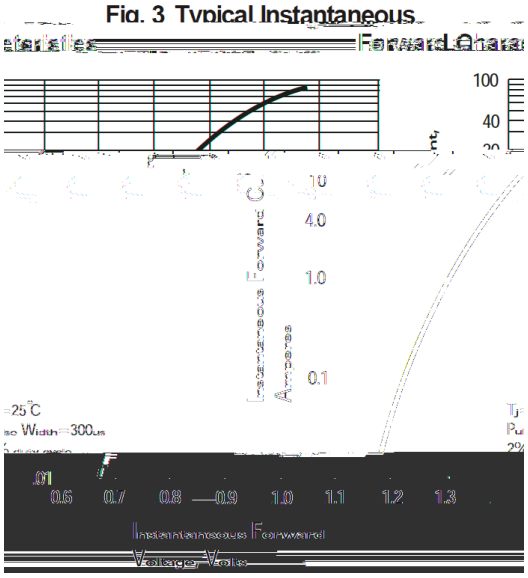


Fig. 4 Typical Reverse Characteristics

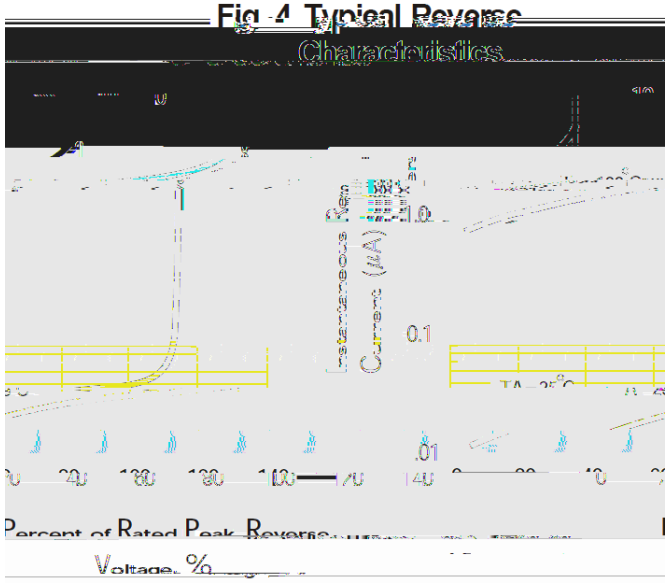
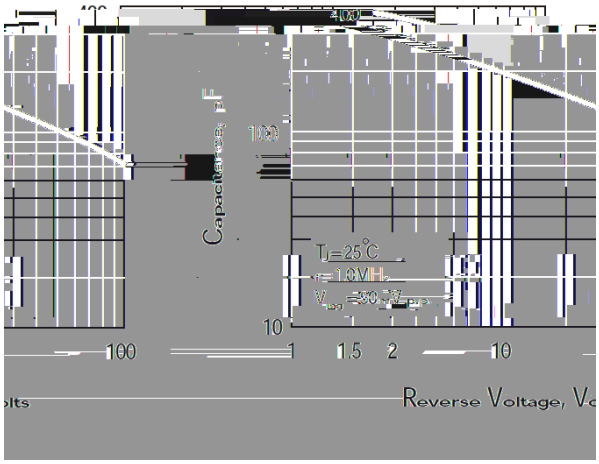
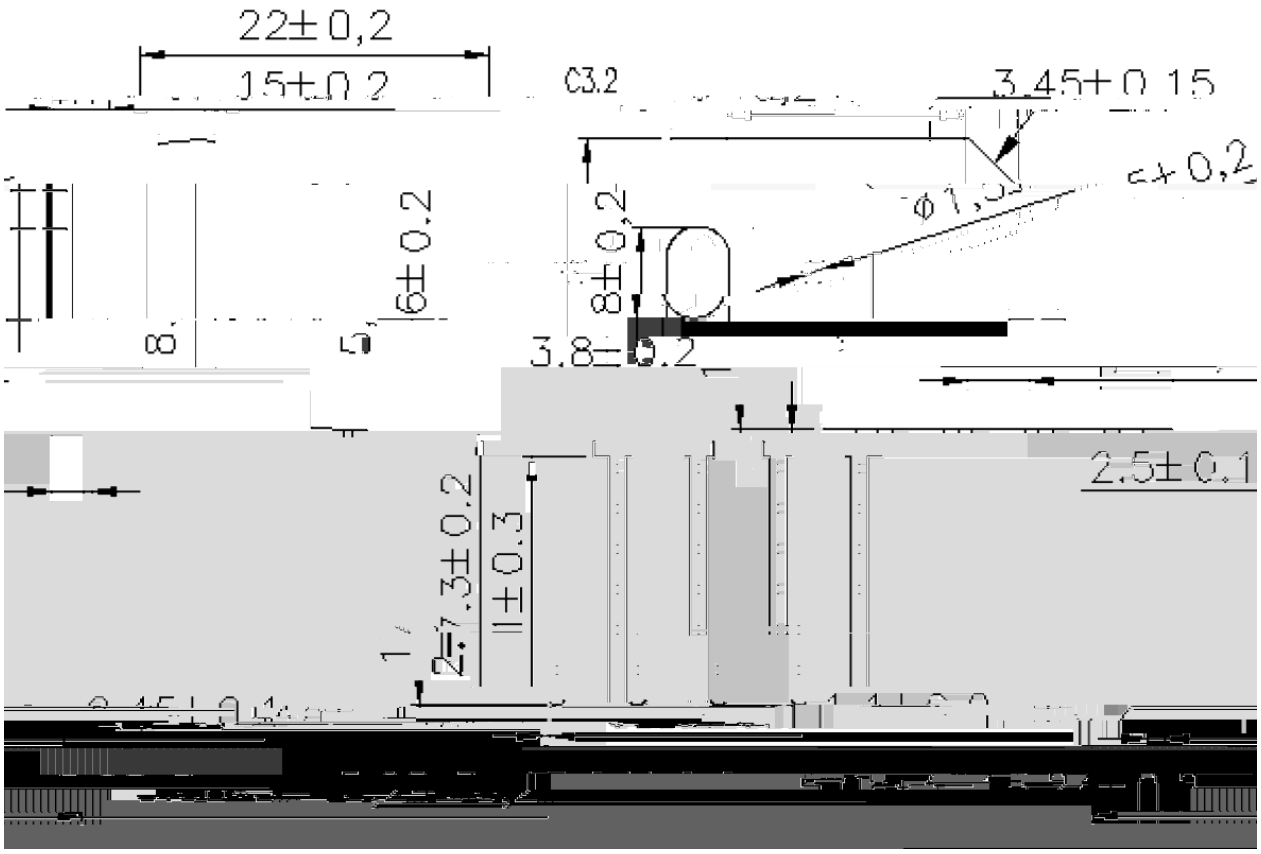


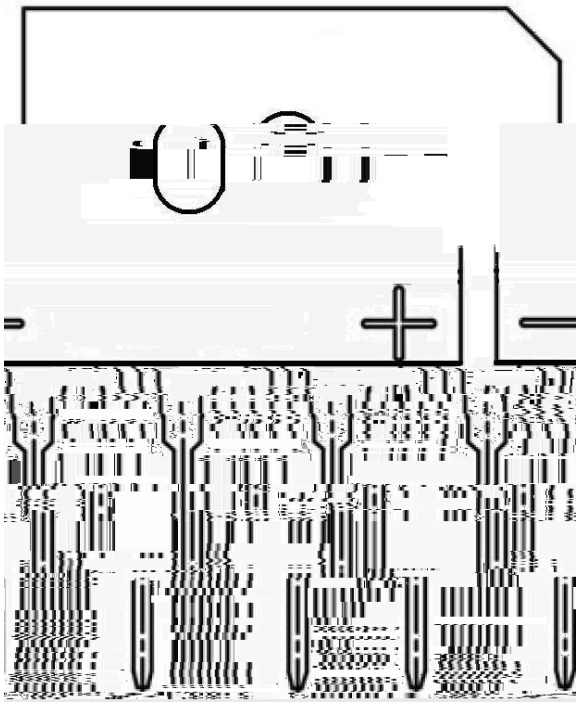
Fig. 5 Typical Junction Capacitance



/ Package Dimensions



/ Marking Instructions



****

( ) / Temperature Profile for Dip Soldering(Pb-Free)

:

1 2 1 0 60 90 ; 1 :2 1 0 :60 90

2 2 ± ±0 ; 2 :2 ± : ±0

3 2 10 3 : 2 10

/ Resistance to Soldering Heat Test Conditions

270± 10±1 :270 :10 1

/ Packaging SPEC.